

IoT SuperServer SYS-212B-FN2T

X14 2U compact front I/O edge AI system with up to 5 PCIe 5.0 slots and redundant AC/DC PSU



Key Applications

AI Inference and Machine Learning, Network Function Virtualization (NFV), Healthcare, Retail, 5G Networking,

Key Features

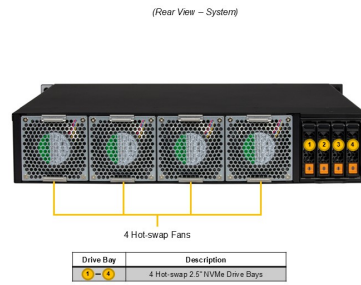
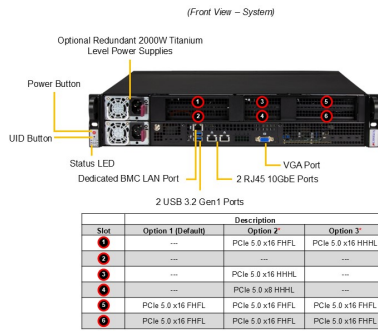
- Single Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores;
- Up to 2TB ECC RDIMM DDR5-6400MT/s or up to 512GB MRDIMM DDR5-8000MT/s in 8 DIMM slots;
- Optional PCIe slot configurations up to 4 PCIe 5.0 x16 (3 FHFL+1 HHHL) slots with support for double-width GPU/Accelerator cards;
- 2x M.2 M-Key NVMe 2280/22110;
- 2x RJ45 10GbE LAN and 1xRJ45 1GbE dedicated IPMI LAN;
- Optional 4 rear 2.5" hot-swap NVMe drive bays;
- Onboard TPM9672: TCG2.0, FiPs 140-2 Level 2, Intel TXT and Microsoft Windows certification;



| | |
|---------------------------------|---|
| Form Factor | 2U Rackmount Enclosure: 437 x 89 x 450mm (17.2" x 3.5" x 17.72") Package: 720 x 266 x 555mm (28.35" x 10.47" x 21.85") |
| Processor | Single Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores P-cores: Up to 86C/172T; Up to 336MB Cache E-cores: Up to 144C/144T; Up to 108MB Cache |
| GPU | Max GPU Count: Up to 2 double-width or 3 single-width GPUs Supported GPU: NVIDIA PCIe: L4, L40S Intel: Arc™ Pro B50 Graphics, Arc™ Pro B60 Graphics (DW), Arc™ Pro B60 Graphics (SW), Arc™ Pro B70 Graphics CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: PCIe |
| System Memory | Slot Count: 8 DIMM slots Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM Max Memory (1DPC): Up to 512GB 8000MT/s ECC DDR5 MRDIMM (P-core only) |
| Drive Bays Configuration | Default: Total 4 bays <ul style="list-style-type: none"> • 4 rear hot-swap 2.5" NVMe* drive bays (*NVMe support may require additional storage controller and/or cables) M.2: 2 M.2 NVMe slots (M-key 2280/22110) |
| Expansion Slots | PCI-Express (PCIe) Configuration: Default <ul style="list-style-type: none"> • 2 PCIe 5.0 x16 (in x16) FHFL slots Option A* <ul style="list-style-type: none"> • 2 PCIe 5.0 x16 (in x16) FHFL slots • 1 PCIe 5.0 x16 (in x16) FHFL double-width slot • 1 PCIe 5.0 x16 (in x16) HHHL slot • 1 PCIe 5.0 x8 (in x8) HHHL slot Option B* <ul style="list-style-type: none"> • 2 PCIe 5.0 x16 (in x16) FHFL slots • 1 PCIe 5.0 x16 (in x16) HHHL slot M.2: 2 M.2 NVMe slots (M-key) |
| On-Board Devices | NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) Network Connectivity: 2 RJ45 10GBASE-T with Intel® X710-AT2 |
| Input / Output | LAN: 1 RJ45 1 GbE Dedicated BMC LAN port 2 RJ45 10 GbE LAN ports USB: 2 USB 3.2 Gen1 Type-A ports(front) |

Video: 1 VGA port

TPM: 1 TPM Onboard TPM & TPM Header



*Requires additional parts from the optional parts list, and limits processor to lower TDP

| | |
|-----------------------|--|
| System Cooling | Fans: Up to 4x 4-PIN PWM 8cm Fan(s) Air Shroud: 1 Air Shroud |
| Power Supply | 1x 2000W Redundant Titanium Level (96%) power supply |
| System BIOS | BIOS Type: AMI 256MB SPI Flash |
| Management | SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New! |
| PC Health Monitoring | CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control Temperature: CPU thermal trip support, PEPI Monitoring for CPU and chassis environment |
| Dimensions and Weight | Weight: Gross Weight: 29 lbs (13.18 kg) Net Weight: 21 lbs (9.55 kg) Available Color: Black |
| Operating Environment | Operating Temperature: 5°C to 40°C (41°F to 104°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing) |
| Motherboard | Super X14SBM-TF |
| Chassis | CSE-223M-R000RCNDP |